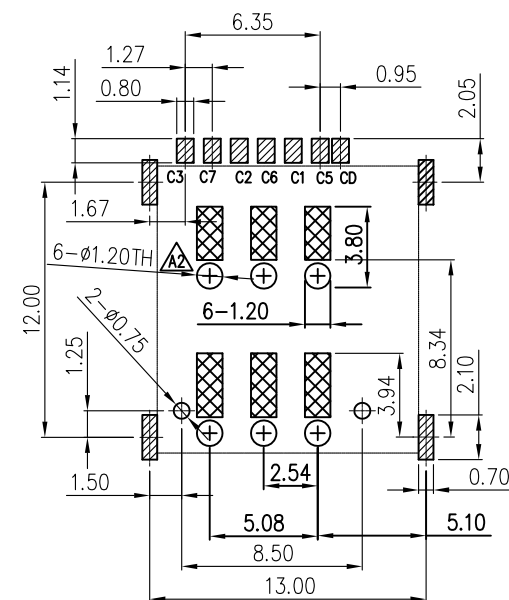
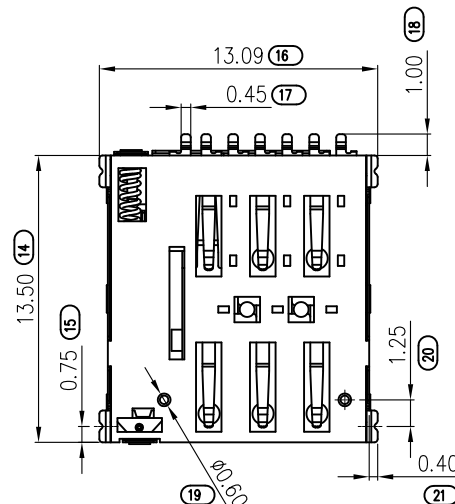
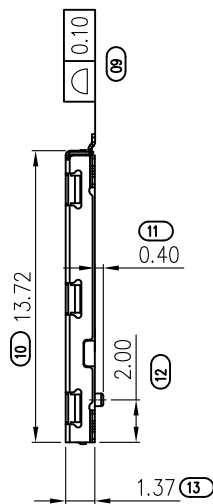
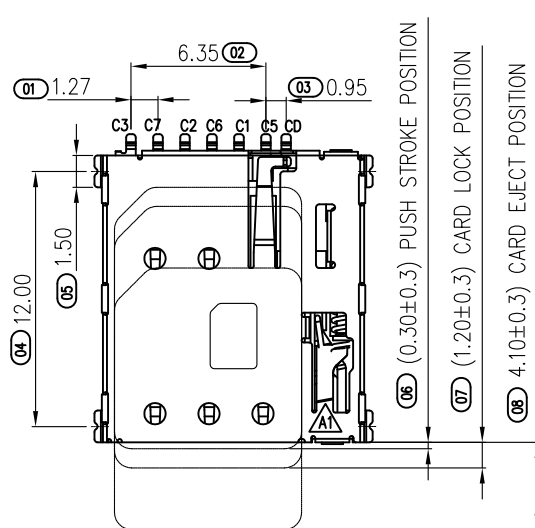


RoHS

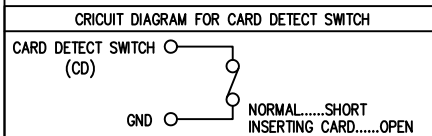
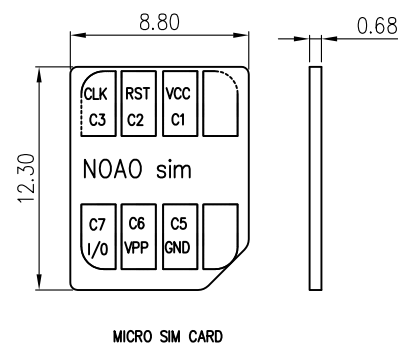
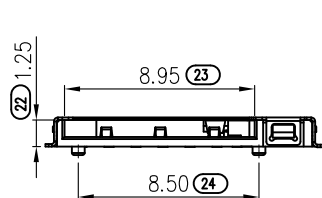
REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A1	ECN1711006	根据外壳修改变更成品, LAYOUT增加KEEP OUT AREA标示	06/11'17	SUPER	SKY	WZX
A2	ECN171200*	根据客户要求变更	05/12'17	SUPER	SKY	WU



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

PAD
 KEEP OUT AREA

- NOTES:
- MATERIAL:
HOUSING: HI-TEMP. PLASIC UL 94V-0
CONTACT: COPPER ALLOY
SHELL: STAINLESS STEEL
 - PLATING :
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: AU GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
 - SPECIALITY:
3.1 Rated current: 1.0A
3.2 Rated voltage: 30V
3.3 Contact Resistance: 50mΩ MAX
3.4 Insulation Resistance: 1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability: 260+0/-5°C, 30±10s.
3.7 Durability: 5000 Cycles Min.
3.8 Operating condition: Temperature -40°C ~ +85°C;
Humidity 80% R.H MAX



SIM pin Assignment		MILLIMETERS	INCH	UNITS				
PIN#	Name	X° ± 2°	X° ±	MAT'L				
C1	VCC	.X ± 0.30	.XX ±	SEE NOTES				
C2	RST	.XX ± 0.20	.XXX ±	FINISH				
C3	CLK	.XXX ± 0.10	.XXXX ±	SEE NOTES				
C5	GND			QTY				
C6	VPP			SEE NOTES				
C7	I/O							

PART NUMBER: 102011612		TITLE: NANO SIM CARD PUSH PUSH 7PIN 1.37H 带CD PIN(客户图)	
APPD:		DWG NO.: C-102011612-00	
CHKD:	DR:	SCALE 1:1	SHEET 1/2
		REV. A2	